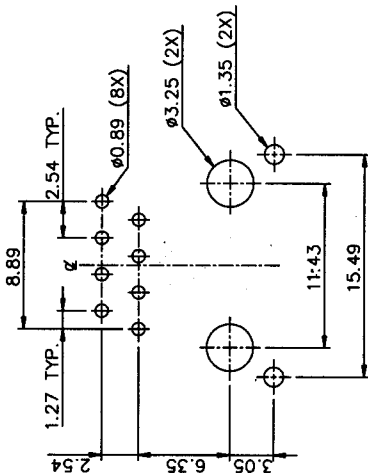
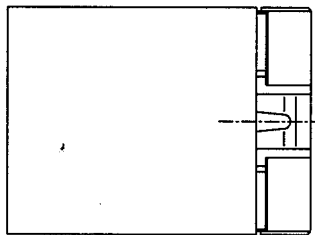
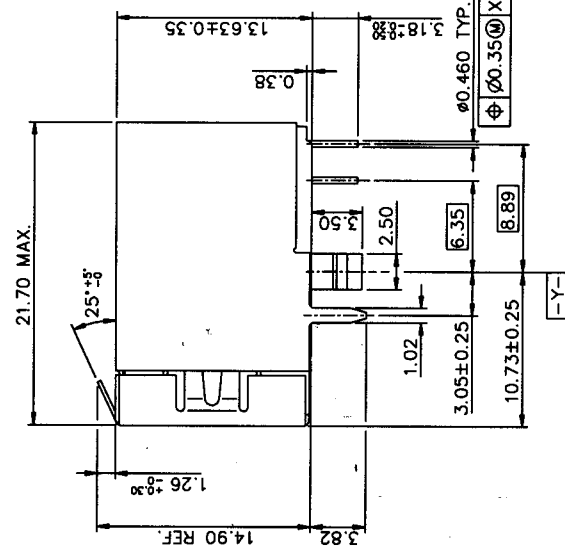
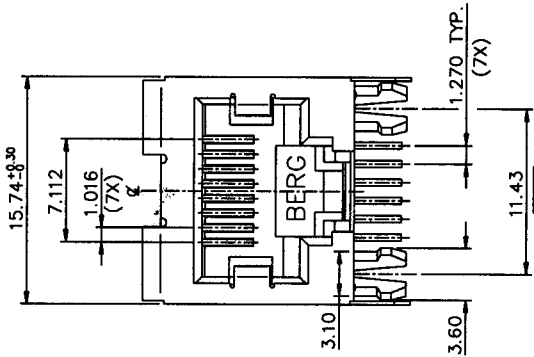


PRODUCT NO.
74523-001N
-001NLF

LEAD FREE PRODUCT NO.



RECOMMENDED PCB LAYOUT



- NOTES:
1. RECOMMENDED P.C.B THICKNESS 1.60 MM
 2. HOUSING MAT'L: HIGH TEMP RESIN.
 3. CONTACTS: PHOS BRONZE ALLOY UNS-C51000, 90.460 ROUND WIRE, PLATING SEE TABLE.
 4. SHIELDING MATERIAL: 0.25MM THICK, COPPER ALLOY. SHIELDING PLATING: 30µ" MIN. NICKEL PLATED.
 5. PACKAGING: USING TRAY.
 6. PART NO. DESCRIPTIONS:
74523 - X 01 N
 7. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
 8. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.60mm MINIMUM THICK CIRCUIT BOARD.
 9. IF LF P/N PACKAGING MEETS GS-14-920 SPECIFICATION.

SHIELDING PLATING:
FOR 30µ" NICKEL PLATING ONLY.

PORT NUMBERS
PLATING CODE:
0=0.76µm/30µ" GXT

mat'l code		tolerance unless otherwise specified		CUSTOMER COPY		FCI	
rev	secn no. dr	date		linear	projection	title	www.fciconnect.com
A	180318	07/21/98	0.00 ± 0.15	0.00 ± 0.15	R/A CAT 5 MOD JACK 8 POS.		
B	103-0413	10/06/03	0.000 ± 0.10	0.000 ± 0.10	SPECIALY SHIELDED SNAP PEG		
C	105-0002	07/11/05	0.000 ± 0.10	0.000 ± 0.10	product family	code	
D	105-0018	07/21/05	0.000 ± 0.10	0.000 ± 0.10	size	dwg no.	
					mm/inch	mm/inch	
					scale	3 : 1	
					sheet	74523	
					1 of 1		
sheet	revision	D					
index	sheet	1					